## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Applicant** 

: Teruhisa ISHIKAWA et al.

Bec'd PCT/PTO

30 NOV 2004

Serial No

: 10/506,609

Filed

: September 10, 2004

For

: BATTERY AND METHOD FOR MANUFACTURING WOUND

ELECTRODE GROUP FOR USE IN THE BATTERY

## INFORMATION DISCLOSURE STATEMENT

U.S. Patent and Trademark Office 220 20th Street S. Customer Window, Mail Stop\_\_\_\_\_\_ Crystal Plaza Two, Lobby, Room 1B03 Arlington, VA 22202

Sir:

In accordance with the duty of disclosure under 37 C.F.R. §1.56, 1.97-1.98, Applicants hereby call the following documents to the Examiner's attention:

JP 6-96801, laid-open April 8, 1994, which is accompanied by an English language translation of the abstract. This document is cited on page 3 of the specification;

JP 8-171917, laid-open November 13, 1998, which is accompanied by an English language translation of the abstract. This document is cited on page 3 of the specification;

JP 10-302827, laid-open November 13, 1998, which is accompanied by an English language translation of the abstract. This document is cited on page 3 of the specification;

JP 10-64577, laid-open March 6, 1998, which is accompanied by an English language translation of the abstract. This document is cited on page 3 of the specification;

JP 60-180071, laid-open September 13, 1985, which is accompanied by an English language translation of the abstract. This document is cited on page 3 of the specification;

- U.S. Patent No. 6,692,542 to KASHIYAMA et al., issued February 17, 2004;
- U.S. Patent Application Publication No. 2004/0061476 to NAKAMARU et al., published April 1, 2004; and
- U.S. Patent Application Publication No. 2004/0048147 to MURAOKA et al., published March 11, 2004.

Furthermore, Applicants call the following documents, which were cited in an International Search Report that was filed concurrently with the application, to the Examiner's attention:

JP 11-121044, laid-open April 30, 1999, which is accompanied by an English language translation of the abstract;

JP 2001-283894, laid-open October 12, 2001, which is accompanied by an English language translation of the abstract;

EP 1102342, published May 23, 2001: U.S. Patent No. 6,509,114 and JP 2001-143762 are patent family members;

JP 07-134984, laid-open May 23, 1995, which is accompanied by an English language translation of the abstract; and

JP 09-283178, laid-open October 31, 1997, which is accompanied by an English language translation of the abstract.

Applicants respectfully request that the Examiner consider and cite the above-noted documents.

Further to the U.S. Patent and Trademark Office's decision to waive the requirement under 37 C.F.R. §1.98 (a)(2)(i), copies of the U.S. patents and U.S. patent application publications are not enclosed herewith. However, if any copies are needed, the Examiner is respectfully requested to contact the undersigned.

Copies of the references, foreign-language documents as well as English language translations of the abstracts of the foreign-language documents, are attached and have been listed on a PTO-1449 Form, which is also attached.

Accordingly, the Examiner is requested to initial the appropriate spaces on the attached PTO-1449 Form and to return a copy of the Form to the Applicants with the next official communication in the present application to confirm consideration of these documents.

If there should be any questions, the Examiner is invited to contact the undersigned at the telephone number listed below.

Respectfully submitted, Teruhisa ISHIKAWA et al.

Bruce H. Bernstein

Reg. No. 29,027

November 23, 2004 GREENBLUM & BERNSTEIN, P.L.C. 1950 Roland Clarke Place Reston, VA 20191 (703) 716-1191

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